



# SOT995-1

plastic thermal enhanced low profile quad flat package; no leads; 48 terminals; body 7 x 7 x 1.2 mm

8 February 2016

Package information

## 1. Package summary

<b>Terminal position code</b>	Q (quad)
<b>Package type descriptive code</b>	HLQFN48R
<b>Package type industry code</b>	HLQFN48R
<b>Package style descriptive code</b>	HLQFN (thermal enhanced low profile quad flatpack; no leads)
<b>Package style suffix code</b>	R (resin based)
<b>Package body material type</b>	P (plastic)
<b>Mounting method type</b>	S (surface mount)
<b>Issue date</b>	14-11-2007

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	6.9	-	7	7.1	mm
E	package width	6.9	-	7	7.1	mm
A	seated height	[tbd]	-	1.2	1.25	mm
A <sub>2</sub>	package height	[tbd]	-	1.2	[tbd]	mm
e	nominal pitch	-	-	0.5	-	mm
n <sub>2</sub>	actual quantity of termination	-	-	48	-	

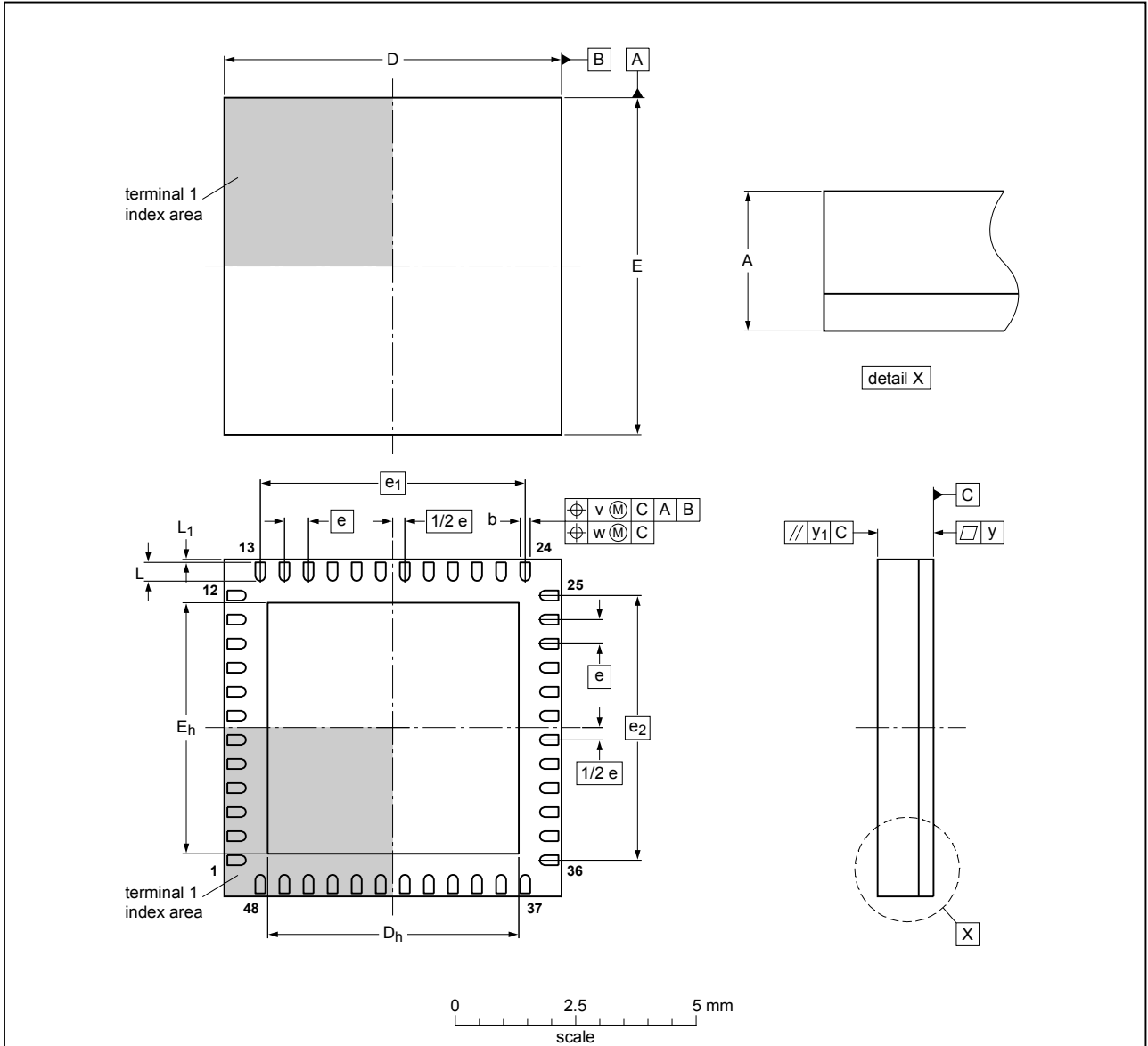


plastic thermal enhanced low profile quad flat package; no leads; 48 terminals; body 7 x 7 x 1.2 mm

## 2. Package outline

HLQFN48R: plastic thermal enhanced low profile quad flat package; no leads; 48 terminals; resin based; body 7 x 7 x 1.2 mm

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DIMENSIONS (mm are the original dimensions)

UNIT	A <sub>max</sub>	b	D	D <sub>h</sub>	E	E <sub>h</sub>	e	e <sub>1</sub>	e <sub>2</sub>	L	L <sub>1</sub>	v	w	y	y <sub>1</sub>
mm	1.25	0.3 0.2	7.1 6.9	4.55 4.53	7.1 6.9	4.52 4.50	0.5	5.5	5.5	0.55 0.45	0.07	0.15	0.05	0.08	0.1

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT995-1	---	---	---			07-08-16 07-11-14

Fig. 1. Package outline HLQFN48R (SOT995-1)

plastic thermal enhanced low profile quad flat  
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mm

### 3. Legal information

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mm

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Date of release: 8 February 2016

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